

6ch Electronic Volume for 5.1ch Car Theater **BD3433K**

General Description

BD3433K is a 6ch electronic volume device for 5.1ch Car Theater. It incorporates various functions such as 6ch input selector (front/rear independently-controlled), input gain amp (front/rear independently-controlled), 6ch independently-controlled electronic volume (capable of soft switching), 6ch output gain amp (2-line outputs), differential input for monophonic signals, electronic volume for monophonic signals (capable of soft switching), and mixing circuit for monophonic signals. It also provides high performance functions to achieve low distortion, low noise and a high voltage output of 5.6Vrms. QFP44 package which offers savings in space and components is used to be suited for applications such as car audio and car navigation.

Features

- High output voltage of 5.6Vrms is achievable Provided with 2 lines of outputs to the built-in power amp and the pre-out.
- Reduces volume switching noise by installing the advanced 6ch independently-controlled electronic volume with soft switching.
- High performance capabilities such as low distortion rate (0.001%), low noise (3µVrms)
- Different signals from different sources can be outputted to the front and rear sections independently and this provides an option of rear-seat entertainment.
- Incorporates monophonic differential input circuit suited for inputting navigation voice and telephone speech.

These monophonic voices can be mixed with the front output signals.

- Energy-saving design resulting in low current consumption, by utilizing the Bi-CMOS process. It has the advantage in quality over scaling down the power heat control of the internal regulators.
- 3-wire serial interface supported for both of 3.3V and 5V microcomputers.

Applications

For car audio equipment, car navigation equipment, and hybrid systems.

Key Specifications

- VCC Power Supply Voltage Range: 7.0V to 9.5V
- VEE Power Supply Voltage Range: -9.5V to -7.0V 0.001%(Typ)
- Total Harmonic Distortion:
- Maximum Input Voltage:
- Cross-talk Between Channels:
- Output Noise Voltage:
- Residual Output Noise Voltage:
- VCO Oscillation Frequency:
- Operating Temperature Range:

W(Typ) x D(Typ) x H(Max)

4.25Vrms(Typ)

106dB(Typ)

2.5µVrms(Typ)

2µVrms(Typ)

400kHz(Typ)

-40°C to +85°C



OProduct structure : Silicon monolithic integrated circuit OThis product has no designed protection against radioactive rays

Typical Application Circuit





Pin Descriptions

Pin No	Pin Name	I/O	Function	Pin No	Pin Name	I/O	Function
1	AGNDE	-	Signal series GND	23	OUTAFR	0	Signal output A for front R ch
2	INAFL	I	Signal input A for front L ch	24	OUTAC	0	Signal output A for center ch
3	INAFR	I	Signal input A for front R ch	25	OUTASW	0	Signal output A for subwoofer ch
4	AGND1	-	Signal series GND	26	OUTARL	0	Signal output A for rear L ch
5	INAC	Ι	Signal input A for centre	27	OUTARR	0	Signal output A for rear R ch
6	INASW	I	Signal input A for subwoofer	28	OUTBFL	0	Signal output B for front L ch
7	AGND2	-	Signal series GND	29	OUTBFR	0	Signal output B for front R ch
8	INARL	I	Signal input A for rear L ch	30	OUTBC	0	Signal output B for center ch
9	INARR	I.	Signal input for A rear R ch	31	OUTBSW	0	Signal output B for subwoofer ch
10	AGND3	-	Signal series GND	32	OUTBRL	0	Signal output B for rear L ch
11	INBFL	I.	Signal input B for front L ch	33	OUTBRR	0	Signal output B for rear R ch
12	INBFR	I	Signal input B for front R ch	34	DGND	-	Digital series ground
13	AGND4	-	Signal series GND	35	SDA	Ι	Micro controller interface (serial data signal input)
14	INBC	Ι	Signal input B for center	36	SCK	Ι	Micro controller interface (serial clock signal input)
15	INBSW	Ι	Signal input B for subwoofer	37	CS	Ι	Micro controller interface (chip select signal input)
16	AGND5	-	Signal series GND	38	TEST	0	Testing terminal
17	INBRL	I	Signal input B for rear L ch	39	ADJ	-	VCC oscillating frequency adjustment
18	INBRR	I	Signal input B for rear R ch	40	VEE	-	Power (negative voltage) input
19	AGND6	-	Signal series GND	41	AGNDM	-	Analog series GND
20	SOUTRL	0	Signal output for rear L ch	42	VCC	-	Power (positive voltage) input
21	SOUTRR	0	Signal output for rear R ch	43	INEX+	Ι	Monaural source signal input
22	OUTAFL	0	Signal output A for front L ch	44	INEX-	Ι	Monaural source signal input

Block Diagram



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit	Terminal
	Vcc-GND	10		(Note 1)
Terminal Applied Voltage	VEE-GND	-10	V	(Note 1)
	VLGC	5.5		Control terminal (CS/SCK/SDA) (Note 1)
Power Dissipation	Pd	0.85	W	(Note 2)
Operating Temperature	Topr	-40 to +85	°C	
Storage Temperature	Tstg	-55 to +125	°C	

(Note 1) Maximum applied voltage based on GND.

(Note 1) Maximum applied Voltage based on OND. (Note 2) Derate by 8.5mW/°C for Ta>25°C. Mounted on (Material: FR4 glass epoxy board (beaten-copper area <3%), size:70mm x 70mm x 1.6mm) Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Recommended Operating Conditions (Ta=25°C)

Parameter	Symbol	Terminal	Min	Тур	Max	Unit	Conditions
Power Supply Voltage	Vcc	Vcc-GND	7.0	9	9.5	V	(Note 1)
Fower Supply voltage	V_{EE}	VEE-GND	-9.5	-9	-7.0	V	(1111)

(Note 1) When it is within operating temperature, basic circuit function is guaranteed within operating voltage. However, setting constant and element, voltage setting, and temperature setting are required when in operation. Other than the conditions stipulated within the range, the standard value of electrical characteristics could not be guaranteed, while original function is retained.

Electrical Characteristics

Abbreviations:

"Giaj" : Setting value of Input gain adjustor

"Vol.Ex" : Setting value of volume for monaural signal "Goajb" : Setting value of output gain adjustor B

"Vol" : Setting value of volume (1ch to 6ch) "Goaja" : Setting value of output gain adjustor A "Mix" : ON/OFF setting for mixing switch.

Measurement condition (Unless specified otherwise) :

Ta=25°C, V_{CC}=9V, V_{EE}=-9V, V_{IN}=1Vrms/1kHz, Load resistance= $10k\Omega$, Load capacitance=10pF, Giaj=0dB, Vol=0dB, Goaja=0dB, Goajb=0dB, Vol.Ex=-∞dB, Mix=OFF

General Characteristics 1.

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Current Consumption	Icc	-	10	17	m 4	
Current Consumption	IEE	-17	-9	-	IIIA	
VCO Oscillation Frequency	fvco	-	400	-	kHz	
Dipple Dejection	RRc	40	85	-	dB	Ripple = 0.1Vrms/ 1kHz (Input terminal AC short)
	RRe	30	70	-	dB	Ripple= 0.1Vrms/ 1kHz (Input terminal AC short)
Reset Operation Voltage	V _{RS}	-	3.4	-	V	Initialize all register data by $V_{CC} < V_{RS}$ to $V_{CC} > V_{RS}$
Required Time for Power ON Reset	t _{POR}	20	-	-	µsec	Minimum required time to reach 3V after VCC voltage ON.

2. Logic Circuit

Parameter	Symbol	Min	Тур	Max	Unit	Terminal
"H" Level Input Voltage	VIH	2.3	-	5.5	V	CS, SCK, SDA
"L" Level Input Voltage	VIL	0	-	1.0	V	CS, SCK, SDA
Input Clock Frequency	fscк	-	-	1.5	MHz	SCK

Electrical Characteristics – continued

3. Volume Circuit

Parameter	Symbol	Min	Тур	Max	Unit		Conditions				
Voltage Gain	Gv	-1	0	+1	dB						
Bandwidth	fw	100	-	-	kHz	Frequency, wh 1kHz	ich drop -1dB towards				
Slew Rate	SR	-	1.65	-	V/µsec						
Maximum Input Voltage	VIM	3.8	4.25	-	Vrms	THD+N = 1% ,	Vol = -10dB				
	V _{OM1}	3.8	4.25	-							
Maximum Output Voltage	V _{OM2}	5	5.6	-	Vrms	THD+N = 1% $Vol = +10dB$	Goaja=+2.5dB				
	Vомз	2.2	2.5	-			Goajb=-4.5dB				
Input Impedance	RIN_V	70k	100k	130k	Ω						
Output Impedance	Rout	-	-	50	Ω						
Input Gain Setting Value Error	Egi	-1	0	+1	dB	Output referen Giaj=6dB, 12d	ce is Giaj=0dB B, V _{IN} =0.1Vrms				
Volume	Ev1	-1.0	0	+1.0		0dB tandard	Vol=+23dB to +1dB, -1dB to -20dB (+23dB to +1dB at V _{IN} =0.1Vrms)				
Setting Value Error	Ev2	-1.5	0	+1.5	aв	/ol=i ut s	Vol=-21dB to -40dB				
	Evз	-2.0	0	+2.0		Dutp V	Vol=-41dB to -60dB				
	Ev4	-3.0	0	+3.0		0	Vol=-61dB to -79dB				
Volume Maximum Attenuation	V _{MU}	-	-108	-85	dB	Vol=-∞dB (mut	e), BW=20Hz to 20kHz				
	Egoa	-1	0	+1		rd Ba	Goaja=+2.5dB				
Output Gain Setting Value Error	Е _{GOB}	-1	0	+1	dB	Goaja Goajb=(Outpu standa	Goajb=-4.5dB				
Gain Balance Between Channels	СВ	-1	0	+1	dB						
Cross-talk Between Channels	CTC	85	106	-	dB	BW=20Hz to 2 (Input terminal	0kHz AC short)				
Output Noise Voltage	V_{NO}	-	2.5	10		BW=A-Weight	Vol=0dB				
Residual Output Noise Voltage	V _{NR}	-	2	10	μVrms	(Input terminal AC short)	Vol=-∞dB				
THD+N	THD	-	0.001	0.05	%	BW=20Hz to 20)kHz, V _{OUT} =1Vrms				
	tss1	-	0.64	-			0.64 msec/dB				
Soft Switching	tss2	-	1.28	-	msec	Soft switching :	g:1.28 msec/dB				
Transition Time	t _{SS3}	-	2.56	-	/dB	ON	2.56 msec/dB				
	t _{SS4}	-	5.12	-			5.12 msec/dB				

Electrical characteristics - continued

4. Monaural Signal Circuit

Common condition unless specified otherwise : Vol=-∞dB, Giaj=Goaja= Goajb=0dB, Vol.Ex=0dB, Mix=ON

	00030 00	B, 101.E	х очв, п			1					
Parameter	Symbol	Min	Тур	Max	Unit	Conditions Phase inversion between input and					
Voltage Gain	Gve	-1.0	0	+1.0	dB	Phase inversion output	n between input and				
Maximum Input Voltage	VIMe	3.8	4.25	-	Vrms	THD+N=1%,	Vol.Ex=-10dB				
Input Impedance	R _{INe}	19	27	35	kΩ						
Volume Setting Value	Eve1	-1.0	0	+1.0		= 0dB tandard	Vol=+15dB to +1dB, -1dB to -20dB, (+15dB +1dB at V _{IN} =0.1Vrms)				
Error	E _{Ve2}	-1.5	0	+1.5	aв	ūt s	Vol=-21dB to -40dB				
	Eve3	-2.0	0	+2.0		Vol	Vol=-41dB to -60dB				
	Eve4	-3.0	0	+3.0		0	Vol=-61dB to -63dB				
Volume Maximum Attenuation	V _{MUe}	-	-108	-85	dB	Vol.Ex=-∞dB (n BW=20Hz to 20	nute) , DkHz				
Output Noise Voltage	V _{NOe}	-	4.5	15		BW=A-Weight	Vol.Ex = 0dB				
Residual Noise Voltage	V _{NRe}	-	3.5	10	μVrms	terminal AC short)	Vol.Ex = -∞dB				
THD+N	THDe	-	0.002	0.05	%	BW=20Hz to 20)kHz, Vou⊤=1Vrms				
Common-Mode Signal Rejection Ratio	CMRR	40	60	-	dB	BW=20Hz to 20)kHz				
	tsse1	-	0.64	-			0.64 msec/dB				
Soft Switching	tsse2	-	1.28	-	msec	Soft	1.28 msec/dB				
Transition Time	tsse3	-	2.56	-	/dB	switching: ON	2.56 msec/dB				
	t _{SSE4}	-	5.12	-			5.12 msec/dB				

Application Information

- 1. Control Signal Specification
 - (1) Timing Chart



Item	Symbol	Min	Тур	Max	Unit	
Input Clock Frequency	fscк	-	-	1.5	MHz	
SCK "High" Interval Width	twнc	200	-	-	nsec	*
SCK "Low" Interval Width	tw∟c	200	-	-	nsec	*
CS "High" Interval Width	twнs	200	-	-	nsec	*
$CS\downarrow$ - $SCK\downarrow$ (Condition of Starting Data Transmission) Set up Time	tssc	400	-	-	nsec	*
SCK \downarrow - CS \downarrow (Condition of Starting Data Transmission) Set up Time	tscs	400	-	-	nsec	*
SDA - SCK↑ (Condition of Starting Data Receiving) Set up Time	tspc	80	-	-	nsec	*
SCK↑ - SDA (Condition of Starting Data Receiving) Hold Time	tнср	80	-	-	nsec	*

(a) When CS is "Low", micro computer control data (SCK/SDA) is enabled. (It doesn't work when CS is "High"),

(b) Data (SDA) is read at the leading edge of clock (SCK).

(c) Latch reads at the leading edge of CS. (SCK has to be kept as "High" after D0 acquisition)

(d) Timing where * mark is not guaranteed by the delivery inspection, but theoretical values on IC design.

(2) Control Data Format Basic Structure Table

("x" · · · don't care bit. Either 0 or 1)

Command		(MS	SB)	Data Transmission Description (Command + Setting data =16 bit) (LSB)													B)	
No	Command name		Com	mano	k					Function De	escrip	otion						
NU.		D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	
0	Backup area	0	0	0	0	х	х	х	х	х	х	х	х	х	х	х	х	
	Selector							Output	Output	Input		Inp	out		Input	Inp	out	
1	Input gain	0	0	0	1	х	х	Gain	Gain	Sel		Ga	ain	х	Sel	Ga	ain	
	Output gain							В	Α	Rear		Rear		ear		Fre	ont	
2	Backup area	0	0	1	0	Х	Х	х	х	х	x x			х	Х	>	x	
3	Monaural Signal	0	0	1	1	Mix	Mix	Transition		Switching			Voli	imo	aain			
3	Moriaurai Signai	0	0	•	•	FRch	FLch	Tir	ne	Pattern			VUIL	une	yam			
4	Backup area	0	1	0	0	х	х	х	х	х	х	Х	х	х	х	х	х	
5	Backup area	0	1	0	1	Х	Х	х	х	х	х	Х	Х	Х	Х	Х	х	
6	Backup area	0	1	1	0	х	х	х	х	х	х	х	х	х	х	х	х	
7	Test sequence	0	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	
8	Volume Front	1	0	0	0	v	v	Trans	sition	Switching			Voli	olume gain				
0	Lch	•	v	v	v	^	^	Tir	ne	Pattern			VOIC	ine	yam			
٩	Volume Front	1	0	0	1	v	v	Trans	sition	Switching			Voli	Imo	nien			
5	Rch	•	Ŭ	Ŭ	•	^	^	Tir	ne	Pattern			VOID	inc	guin			
10	Volume Center	1	0	1	0	x	x	Trans	sition	Switching			Voli	ime	nain			
10	ch	-	•	-	•	^	^	Tir	ne	Pattern			VOIC		guin			
11	Volume	1	0	1	1	x	x	Trans	sition	Switching			Voli	ıme	aain			
	Subwoofer ch	-	-		_	~	~	Tir	ne	Pattern					94			
12	Volume Rear	1	1	0	0	х	х	Trans	sition	Switching			Volu	ıme	aain			
	Lch				-			Time		Pattern					9			
13	Volume Rear	1	1	0	1	х	х	Transition		Switching			Volu	ume	gain			
	Rcn	4	-	_	•			time		Pattern							-	
14	Backup area	1			U	Х	Х	X X		Х	Х	Х	Х	Х	Х	Х	Х	
15	Backup area	1	1	1	1	Х	Х	X X		Х	Х	Х	Х	Х	Х	Х	Х	

In changing command setting value, enable to select command from No.0 to No.15 Transmission has to be every 16bit as above format.

(3) Initial Value when Power Source is ON.

When power is ON, built-in power on reset circuit initializes setting data to bit "0" (Low) within the IC. However, just in case of set design stage, initial data has to be sent to all addresses when turning power ON, and mute setting is recommended during this initial data transmission.

(4) Preventive Measure for Malfunction by Electrostatic Surge

The IC's logic circuit has shift registers to retain 16bit serial data which is external input from micon etc. The data, which is retained by shift registers, will be synchronized with CS signal leading edge, then is latched to each function. Therefore, if electrostatic surge is applied to the logic signal terminal (CS, SCK, SDA), inappropriate latch may cause malfunction of internal circuit. As a preventive measure for malfunction, 0000(hex) data transmission for command No.0 (backup area), at the end of every data transmission to specific command to initialize shift register in the IC is recommended.

								("X"	•••	Eith	er U	or 1)					
		(MS	B)	Tran	smis	sion	data	a (co	mma	and -	⊦ Set	tting	data	ι =16	bit)	(LS	B)
Function	Setting	(Com	man	d					S	ettin	g da	ta				
		D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Command		0	0	0	1	х	х	-	-	-	-	-	-	х	-	-	-
Input gain Front ch Center ch Subwoofer ch	(Initial value) 0 dB 0 dB +6 dB +12 dB	Ŷ	¢	Ŷ	Ţ	x	x	-	-	-	-	-	-	x	-	0 0 1 1	0 1 0 1
Input selector Front ch Center ch Subwoofer ch	(Initial value) Input A Input B	ţ	¢	ţ	ţ	x	x	-	-	-	-	-	-	x	0 1	-	-
Input Gain Rear ch	(Initial value) 0 dB 0 dB +6 dB +12 dB	¢	¢	î	ţ	x	x	-	-	-	-	0 0 1 1	0 1 0 1	x	-	-	-
Input selector Rear ch	(Initial value) Rear input A Rear input B Front input A Front input B	¢	¢	ſ	¢	x	x	-	-	0 0 1 1	0 1 0 1	-	-	x	-	-	-
Output gain A	(Initial value) 0 dB +2.5 dB	î	î	î	ſ	х	х	-	0 1	-	-	-	-	х	-	-	-
Output gain B	(Initial value) 0 dB -4.5 dB	1	¢	î	1	x	x	0 1	-	-	-	-	-	x	-	-	-

(5) Command No.1 "Selector, Input Gain, Output Gain" Setting Data Chart

		(MS	SB)	Tra	nsm	issio	n dat	ta (co	omm	and	+ set	tting	data	=16b	oit)	(LS	B)
Function	Setting data	(Comi	man	d		-			S	ettin	g da	ta		1		
		D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Command		0	0	1	1	-	-	-	-	-	-	-	-	-	-	-	-
Command	(Initial value) -∞dB(MUTE) +15 dB +14 dB +13 dB +12 dB : : : +9 dB +8 dB +7 dB	0	0	1	1	-	-	-	-	-	- 0 1 : 1 1 1 1 : : 1 1 1 : : : : : : : :	- 0 1 : 1 1 1 1 : : 1 1 1 : : : : : : : :	- 0 1 : 1 1 1 1 1 : : 1 0 :	- 0 1 : : 0 0 0 0 0 : : : 0 0 1 : :	- 0 1 : 1 1 1 1 : : 0 0 1 :	- 0 1 : : 1 1 0 0 : : 0 0 1 : :	- 0 1 : : 1 0 1 0 : : 1 0 1 : :
Volume gain	+2 dB +1 dB 0 dB -1 dB -2 dB : : : -7 dB -8 dB -9 dB : : : : -40 dB -41 dB : : : : -62 dB -63 dB	Î	Î	↑ 	↑ 	-	-	-	-	-	· : 1 1 1 1 : : 1 1 : : 1 0 : 0 0	· 1 1 1 1 1 1 1 1 1 1 1 1 1	0 0 0 0 0 0 0 0 0 0 0 1 : : 0 0 1 : : 0 0 1 : : 0 0 0 0	: 1 1 0 0 : : 0 0 1 : : 1 1 Else	: 0 0 1 1 : : 0 0 1 : : 0 0 1 : : 0 0 1 : : 0 0 1 : : 0 0 0 0	: 1 0 0 1 1 : : 0 0 1 : : 0 1 : : 1 0	0 1 0 1 0
Volume switching pattern	(Initial value) Secondary Soft switching	ſ	¢	î	î	-	-	-	-	0 1	-	-	-	-	-	-	-
Volume switching transition time	(Initial value) 0.64(msec/dB) 1.28 (msec/dB) 2.56 (msec/dB) 5.12 (msec/dB)	Ţ	1	¢	Ţ	-	-	0 0 1 1	0 1 0 1	-	-	-	-	-	-	-	-
Mixing Front Lch	(Initial value) OFF	1	1	Î	Î	-	0	-	-	-	-	-	-	-	-	-	-
Mixing Front Rch	(Initial value) OFF ON	1	ſ	î	î	0 1	-	-	-	-	-	-	-	-	-	-	-

Datasheet

- (7) Command No.8 Command No.9 Command No.10 Command No.11 Command No.12 Command No.13
- "Volume front L ch" "Volume front R ch" "Volume center ch" "Volume subwoofer ch" "Volume rear L ch" "Volume rear R ch"

Setting data chart						("x'	· · · ·	E	ither	0 0	1)						
		(MS	SB)	Trar	ismis	ssior	n dat	a (co	mm	and	+ se	tting	data	ι=16	bit)	(LS	B)
Function	Setting	C	Comr	nano	k					S	ettin	g dat	ta				
		D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
	Volume FL ch	1	0	0	0												
	Volume FR ch	1	0	0	1												
Command	Volume C ch	1	0	1	0	х	х	-	-	-	-	-	-	-	-	-	х
	Volume SVV ch	1	0	1	1												
	Volume RL Ch	1	1	0	1												
	(Initial Value) -@dB(MLITE)	•	•	v	•						0	0	0	0	0	0	0
	+23 dB										1	1	1	1	1	1	1
	+22 dB										1	1	1	1	1	1	0
	+21 dB										1	1	1	1	1	0	1
	-										•	•	•	-	•	•	•
	:										:	:	:	:	:	:	:
	+9 dB										1	1	1	0	0	0	1
	+8 dB										1	1	1	0	0	0	0
	+7 dB										1	1	0	1	1	1	1
	:										:	:	:	:	:	:	:
														-			
	- 2 dB																
	+2 0B +1 dB										1	1	0	1	0	0	1
		↑	†	↑	↑	v	v	_	_	_	1	•	0	• 1	0	0	•
			I	I	I	^	^				•	•	0	•	4	4	4
	-1 OB										1	1	0	0	1	1	1
Volume gain	-2 UB											•	U	U	•		U
	:										:	:	:	:	:	:	:
	:										:	:	:	:	:	:	:
	-7 dB										1	1	0	0	0	0	1
	-8 dB										1	1	Õ	Õ	Õ	Õ	0
	-9 dB										1	0	1	1	1	1	1
	-										•	•	•	-	•	•	•
	:										:	:	:	:	:	:	:
	-40 dB										1	0	0	0	0	0	0
	-41 dB										0	1	1	1	1	1	1
	:										:	:	:	:	:	:	:
														-			
	-78 dB -79 dB										0	0	1	1	0	0	1
											•	•	-			•	
	-∞dB(MUTE)													EISE			
Volume switching	(Initial value)	•	•		*					0							,
Pattern	Secondary Soft switching	Ť	T	ſ	Î	х	x	-	-	1	-	-	-	-	-	-	Х
	(Initial value)									1							
	0.64 (msec/dB)							0	0								
Volume switching	1.28 (msec/dB)	↑ (↑	↑	↑	х	х	0	1	-	-	-	-	-	-	-	х
transition time	2.56 (msec/dB)							1	0								
	5.12 (msec/dB)							1	1								

2. Application Circuit Example



ľ	1	:	Oscillation countermeasure]	
-		•		

Using higher capacity than 10pF may cause oscillation.

As oscillation countermeasure, insert series resistor to terminal directly as below.

Capacity	type Series resister	
C < 10pF	(Not necessary)	
10pF < C < 100pF	100Ω	
100pF < C < 1000pF	100Ω	



Resistor for oscillation countermeasure

[2 : Mounting pattern]

- $\cdot\,$ Wire a GND line to the GND point which becomes a standard by the independence.
- $\cdot\,$ Wiring pattern of CS, SCK and SDA should be away from the analog lines to avoid cross-talk.
- · Input lines should not be parallel if possible. The lines should be shielded, if they are adjacent to each other.
- Please connect the resistor (39k Ω) for adjusting VCO frequency to ADJ terminal in the shortest distance possible.

1dB/step 1dB/step

(1) Volume Control Description

(Bo	ld with underline is initial setting value)
(a)	Volume setting value

The Setting value		
(For 5.1ch signal)	: +23dB to -79dB, <u>-∞dB(mut</u>	e) ,
(For Monaural signal)	: +15dB to -63dB, -∞dB(mute	e) ,

- (b) Selection of switching formula :
 - Secondary switching, soft switching
- (c) Soft switching transition time (Transition time/dB) :

0.64 / 1.28 / 2.56 / 5.12 [msec/dB] (*)



(2) In case of receiving following setting command during volume changing Terminate current transition and start next transition. Switching volume can be done with only 1dB/step, so termination or restart of transi

Switching volume can be done with only 1dB/step, so termination or restart of transition is on timing of 1dB/step basis.



(Figure notes) When setting command example1, volume gain drops from -20dB to -30dB with 2.56msec/dB. In the figure, when setting command example 2 during a transition from -27dB to -28dB, command example 2 will be set when it reaches -28dB because termination or restart can be done every 1dB unit.

I/O Equivalent Circuits

Terminal Number	Terminal Name	I/O	Terminal Voltage	Terminal Equivalent Circuits
2 3 5 6 8 9 11 12 14 15 17 18	INAFL INAFR INAC INASW INARL INBFL INBFR INBC INBSW INBRL INBRR	Ι	ov	VCC OF TOOL OF
43	INEX+	I	ov	VCC OF TI3.5k
44	INEX-	I	ov	VCC OF
20 21 22 23 24 25 26 27 28 29 30 31 32 33	SOUTRL SOUTAR OUTAFL OUTAFR OUTAC OUTASW OUTARL OUTBFL OUTBFR OUTBFR OUTBSW OUTBRL OUTBRR	0	0V	VCC OFFICIENCE

I/O Equivalent Circuits – continued

Terminal Number	Terminal Name	I/O	Terminal Voltage	Terminal Equivalent Circuits	
35 36 37	SDA SCK CS	I	-	VCC O SK SK SK SK SK SK SK SK SK SK	
39	ADJ	-	0.7V	AGNDM OVER OVER OVER OVER OVER OVER OVER OVER	
1 4 7 10 13 16 19 34 41	AGNDE AGND1 AGND2 AGND3 AGND4 AGND5 AGND6 DGND AGNDM	-	ov		
42 40	VCC VEE	-	8.3V -8.3V	VCC O	

Operational Notes

1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. VEE Voltage

Ensure that no pins are at a voltage below that of the VEE pin at any time, even during transient condition.

4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

Operational Notes – continued

12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When VEE > Pin A and VEE > Pin B, the P-N junction operates as a parasitic diode. When VEE > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the VEE voltage to an input pin (and thus to the P substrate) should be avoided.



Figure 1. Example of monolithic IC structure

Ordering Information



Marking Diagram





Revision History

Date	Revision	Changes
16.Dec.2015	001	New Release

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 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
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 - [d] the Products are exposed to high Electrostatic
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